

Appl. No. 10/040,027  
Amdt. dated June 23, 2004  
Reply to Office Action of April 5, 2004

**Amendments to the Specification:**

Please replace the paragraph extending from page 3, line 12 to line 23, with the following rewritten paragraph:

In accordance with another alternative embodiment of the present invention, an image sensor package includes a transparent substrate having a rear surface and a front surface. A rear trace is coupled to the rear surface and a front trace is coupled to the front surface. A via extends from the rear surface to the front surface and electrically couples the rear trace to the front trace. An image sensor includes a first surface having an active area and a bond pad.

A bump couples the bond pad to the rear trace. A bead forms a seal between a periphery of the image sensor and the rear surface. A package body encloses the bead and a side of the image sensor.